

Sound Processor with Built-in 3-band Equalizer

BD37544FS

General Description

BD37544FS is a sound processor with built-in 3-band equalizer for car audio. The functions are stereo input selector (which can switch single and GND isolation), input-gain control, main volume, super bass, 5ch fader volume, LPF/HPF for subwoofer, and mixing input. Moreover, "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). Also, "Advanced switch" makes control of microcomputer easier, and can construct a high quality car audio system.

Features

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, middle, treble, super bass, mixing by using advanced switch circuit.
- Built-in differential input selector that can make various combination of single-ended / differential input.
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces switching noise for volume of a portable audio input.
- Decreased number of external components due to built-in 3-band equalizer filter, LPF for subwoofer, and HPF. It is possible to control Q, Gv, fo of 3-band equalizer and fc of LPF/HPF through I²C BUS control.
- It is possible to adjust the gain of the bass, middle, and treble up to ±20dB with 1 dB step gain adjustment.
- It is equipped with output terminals for Subwoofer. Moreover, the stereo signal output of the front and rear can also be chosen by the I²C BUS control.
- Built-in mixing input and mixing attenuator.
- Energy-saving design resulting in low-current consumption is achieved by utilizing the Bi-CMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input terminals and output terminals are organized and separately laid out to keep the signal flow in one direction which results in simpler and smaller PCB layout.
- It is possible to control the I²C BUS by 3.3V / 5V.

Applications

It is optimal for car audio systems. It can also be used for audio equipment of mini Compo, micro Compo, TV, etc.

Key Specifications

Power Supply Voltage Range: 7.0V to 9.5VCircuit Current (No Signal): 38mA (Typ)

■ Total Harmonic Distortion:

THD+N1 0.001% (Typ)
THD+N2 0.002% (Typ)

Maximum Input Voltage: 2.3Vrms(Typ)
Cross-talk Between Selectors: -100dB(Typ)
Volume Control Range: +15 dB to -79dB
Output Noise Voltage:

 $\begin{array}{c} V_{NO1} & 3.8 \mu V rms (Typ) \\ V_{NO2} & 4.8 \mu V rms (Typ) \\ Residual Output Noise Voltage: 1.8 \mu V rms (Typ) \end{array}$

Operating Temperature Range: -40°C to +85°C

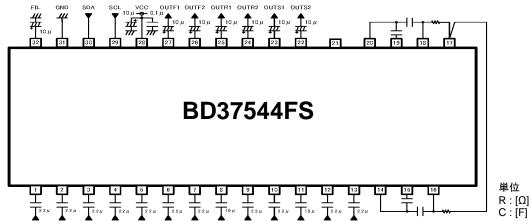
Package

W(Typ) x D(Typ) x H(Max)

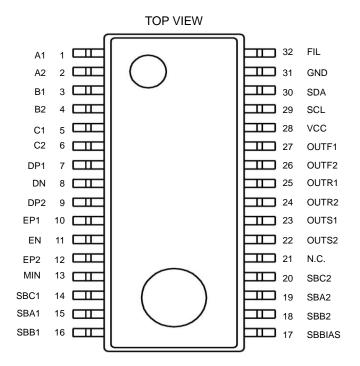


SSOP-A32 13.60 mm x 7.80mm x 2.01mm

Typical Application Circuit



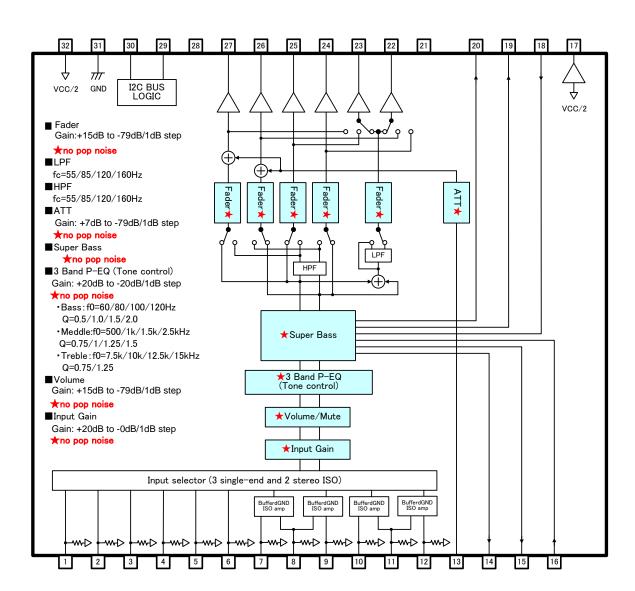
Pin Configuration



Pin Descriptions

Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	17	SBBIAS	SuperBass bias terminal
2	A2	A input terminal of 2ch	18	SBB2	SuperBass setting terminal of 2ch
3	B1	B input terminal of 1ch	19	SBA2	SuperBass setting terminal of 2ch
4	B2	B input terminal of 2ch	20	SBC2	SuperBass setting terminal of 2ch
5	C1	C input terminal of 1ch	21	N.C.	No connection
6	C2	C input terminal of 2ch	22	OUTS2	Subwoofer output terminal of 2ch
7	DP1	D positive input terminal of 1ch	23	OUTS1	Subwoofer output terminal of 1ch
8	DN	D negative input terminal	24	OUTR2	Rear output terminal of 2ch
9	DP2	D positive input terminal of 2ch	25	OUTR1	Rear output terminal of 1ch
10	EP1	E positive input terminal of 1ch	26	OUTF2	Front output terminal of 2ch
11	EN	E negative input terminal	27	OUTF1	Front output terminal of 1ch
12	EP2	E positive input terminal of 2ch	28	VCC	Power supply terminal
13	MIN	Mixing input terminal	29	SCL	I ² C Communication clock terminal
14	SBC1	SuperBass setting terminal of 1ch	30	SDA	I ² C Communication data terminal
15	SBA1	SuperBass setting terminal of 1ch	31	GND	GND terminal
16	SBB1	SuperBass setting terminal of 1ch	32	FIL	VCC/2 terminal

Block Diagram



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	Vcc	10.0	٧
Input Voltage	V_{IN}	V _{CC} +0.3 to GND-0.3	٧
Power Dissipation	Pd	0.95 (Note 1)	W
Storage Temperature	Tstg	-55 to +150	°C

⁽Note 1) When mounted on the standard board (70 x 70 x 1.6 mm³), derate by 7.6mW/°C for Ta above 25°C.

Thermal resistance θja = 131.6(°C/W)

Material: A FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol	Min	Тур	Max	Unit
Power Supply Voltage	V _{CC}	7.0	-	9.5	V
Temperature	Topr	-40	-	+85	°C

Electrical Characteristics

(Unless specified, Ta=25°C, Vcc=8.5V, f=1kHz, V_{IN}=1Vrms, Rg=600 Ω , R_L=10k Ω , A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, LPF OFF, HPF OFF, Mixing OFF, Fader 0dB)

	le dab, Tone control dab, Loudnes		<u> </u>	Limit	iixiiig Oi		
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Circuit Current (No Signal)	lα	-	38	48	mA	No signal
	Voltage Gain	G∨	-1.5	0	+1.5	dB	G _V =20log(V _{OUT} /V _{IN})
	Channel Balance	СВ	-1.5	0	+1.5	dB	$CB = G_{V1} - G_{V2}$
	Total Harmonic Distortion 1 (FRONT, REAR)	THD+N1	-	0.001	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
GENERAL	Output Noise Voltage 1 (FRONT,REAR) *	V_{NO1}	-	3.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
GEN	Output Noise Voltage 2 (SUBWOOFER) *	V _{NO2}	-	4.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
	Residual Output Noise Voltage*	V _{NOR}	-	1.8	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A
	Cross-talk Between Channels *	СТС	-	-100	-90	dB	$Rg = 0\Omega$ $CTC=20log(V_{OUT}/V_{IN})$ $BW = IHF-A$
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V _{RR} =100mVrms RR=20log(V _{CC} IN/V _{ОUТ})
	Input Impedance(A, B,C)	R _{IN_S}	70	100	130	kΩ	
~	Input Impedance(D, E)	R _{IN_D}	175	250	325	kΩ	
ECTOF	Maximum Input Voltage	V_{IM}	2.1	2.3	ı	Vrms	V _{IM} at THD+N(V _{OUT})=1% BW=400Hz-30KHz
INPUT SELECTOR	Cross-talk Between Selectors *	CTS	-	-100	-90	dB	Rg = 0Ω CTS= $20log(V_{OUT}/V_{IN})$ BW = IHF-A
INPI	Common Mode Rejection Ratio*	CMRR	50	65	-	dB	XP1 and XN input XP2 and XN input CMRR=20log(V _{IN} /V _{OUT}) BW = IHF-A,[*XD,E]

Electrical Characteristics - continued

ctrica	al Characteristics - continued	l					
Š	Dozomator	C) wash al		Limit		l lait	Conditions
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
NIA	Minimum Input Gain	GIN_MIN	-2	0	+2	dB	Input gain 0dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
INPUT GAIN	Maximum Input Gain	G _{IN_MAX}	18	20	22	dB	Input gain 20dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
	Gain Set Error	GIN_ERR	-2	0	+2	dB	GAIN=+20dB to +1dB
MUTE	Mute Attenuation *	G _{мите}	1	-105	-85	dB	Mute ON G _{MUTE} =20log(V _{OUT} /V _{IN}) BW = IHF-A
	Maximum Gain	G _{V_MAX}	13	15	17	dB	Volume = 15dB V_{IN} =100mVrms G_V =20log(V_{OUT}/V_{IN})
VOLUME	Maximum Attenuation *	Gv_min	-	-100	-85	dB	$\label{eq:Volume} \begin{split} &\text{Volume} = -\infty dB \\ &G_V \!\!=\!\! 20 log(V \ V_{OUT} \!/\! V_{IN}) \\ &BW = IHF \!\!-\!\! A \end{split}$
0	Attenuation Set Error 1	G _{V_ERR1}	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB
	Attenuation Set Error 2	G _{V_ERR2}	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	Gv_err3	-4	0	+4	dB	ATT=-48dB to -79dB
	Maximum Boost Gain	G _{B_BST}	18	20	22	dB	Gain=+20dB f=100Hz V _{IN} =100mVrms G _B =20log (V _{OUT} /V _{IN})
BASS	Maximum Cut Gain	G в_сит	-22	-20	-18	dB	Gain=-20dB f=100Hz V _{IN} =2Vrms G _B =20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{B_ERR}	-2	0	+2	dB	Gain=-20dB to +20dB f=100Hz
щ	Maximum Boost Gain	G _{M_BST}	18	20	22	dB	Gain=+20dB f=1kHz V _{IN} =100mVrms G _M =20log (V _{OUT} /V _{IN})
MIDDLE	Maximum Cut Gain	G м_сит	-22	-20	-18	dB	Gain=-20dB f=1kHz V _{IN} =2Vrms G _M =20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{M_ERR}	-2	0	+2	dB	Gain=-20dB to +20dB f=1kHz
Щ	Maximum Boost Gain	G _{T_BST}	18	20	22	dB	Gain=+20dB f=10kHz V _{IN} =100mVrms GT=20log (V _{OUT} /V _{IN})
TREBLE	Maximum Cut Gain	Gт_сит	-22	-20	-18	dB	Gain=-20dB f=10kHz V _{IN} =2Vrms G _T =20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{T_ERR}	-2	0	+2	dB	Gain=-20dB to +20dB f=10kHz
	Input Impedance	R _{IN_M}	19	27	35	kΩ	
9 N	Maximum Input Voltage	V _{IМ_М}	2.0	2.2	-	Vrms	V _{IM} at THD+N(V _{OUT})=1% BW=400Hz-30KHz
MIXING	Maximum Attenuation *	G _{MX_MIN}	-	-100	-85	dB	MIX=OFF G _{MX} =20log(V _{OUT} /V _{IN}) BW=INF-A
	Maximum Gain	G _{MX_MAX}	5	7	9	dB	ATT=+7dB G _{MX} =20log(V _{OUT} /V _{IN})

Electrical Characteristics - continued

,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		4					
BLOCK	Parameter	Symbol		Limit		Unit	Conditions
BLC	Parameter	Symbol	Min	Тур	Max	Offic	Conditions
	Maximum Boost Gain	G _{F_BST}	13	15	17	dB	Fader=15dB V _{IN} =100mVrms G _F =20log(V _{OUT} /V _{IN})
SUBWOOFER	Maximum Attenuation *	G _{F_MIN}	1	-100	-90	dB	Fader = $-\infty$ dB $G_F=20\log(V_{OUT}/V_{IN})$ BW = IHF-A
BWC	Gain Set Error	G _{F_ERR}	-2	0	+2	dB	GAIN=+1dB to +15dB
/SU	Attenuation Set Error 1	G _{F_ERR1}	-2	0	+2	dB	ATT=-1dB to -15dB
FADER	Attenuation Set Error 2	G _{F_ERR2}	-3	0	+3	dB	ATT=-16dB to -47dB
FAC	Attenuation Set Error 3	G _{F_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
-	Output Impedance	Rout	-	-	50	Ω	V _{IN} =100mVrms
	Maximum Output Voltage	V _{OM}	2	2.2	-	Vrms	THD+N=1% BW=400Hz-30KHz

VP-9690A(Average value detection, effective value display) filter by Matsushita Communication is used for * measurement. Phase between input / output is same.

Typical Performance Curves

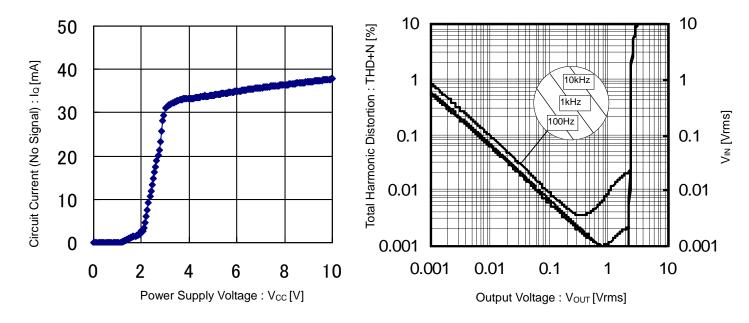


Figure 1. Circuit Current (No Signal) vs Power Supply Voltage

Figure 2. Total Harmonic Distortion vs Output Voltage

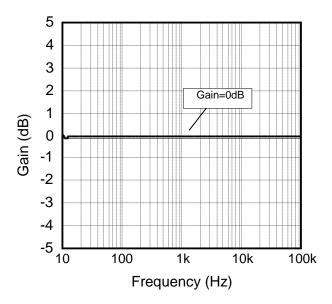


Figure 3. Gain vs Frequency

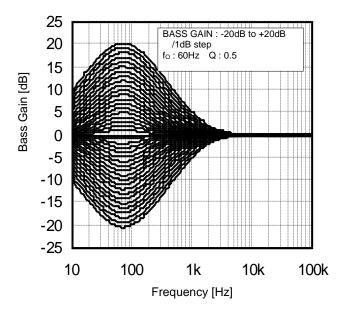


Figure 4. Bass Gain vs Frequency

Typical Performance Curves – continued

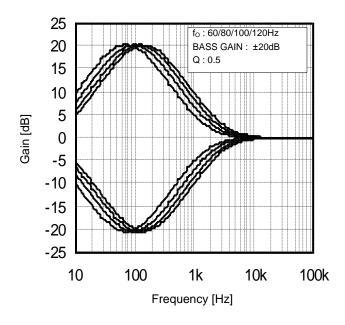


Figure 5. Bass fo vs Frequency

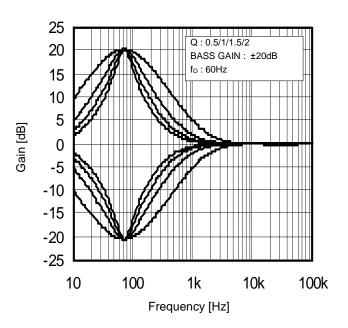


Figure 6. Bass Q vs Frequency

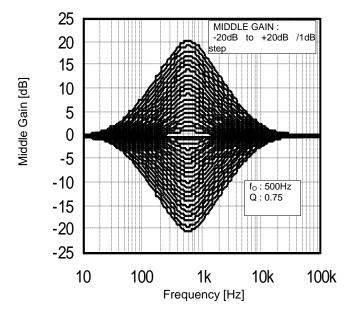


Figure 7. Middle Gain vs Frequency

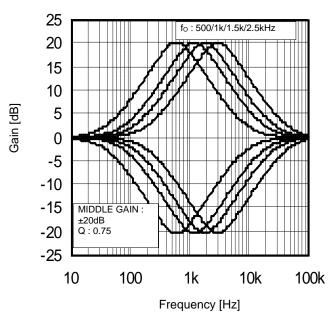


Figure 8. Middle fo vs Frequency

Typical Performance Curves – continued

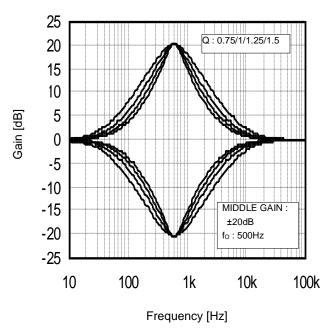


Figure 9. Middle Q vs Frequency

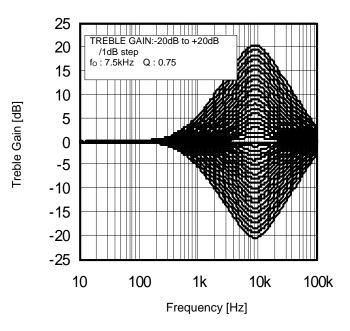


Figure 10. Treble Gain vs Frequency

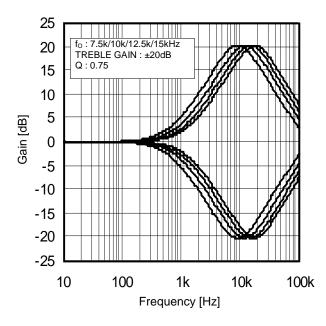


Figure 11. Treble fo vs Frequency

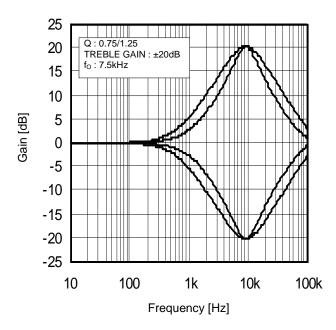


Figure 12. Treble Q vs Frequency

Typical Performance Curves – continued

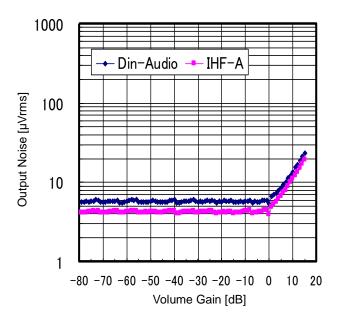


Figure 13. Output Noise vs Volume Gain

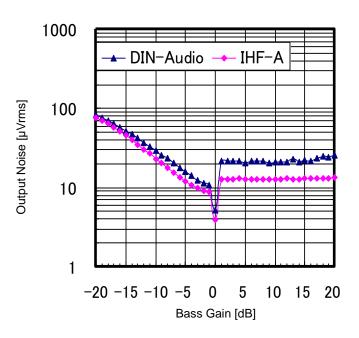


Figure 14. Output Noise vs Bass Gain

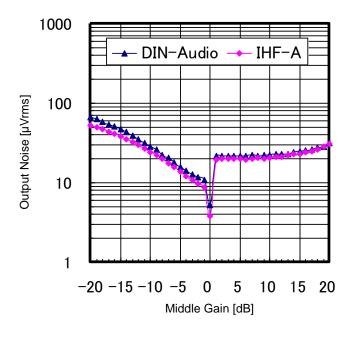


Figure 15. Output Noise vs Middle Gain

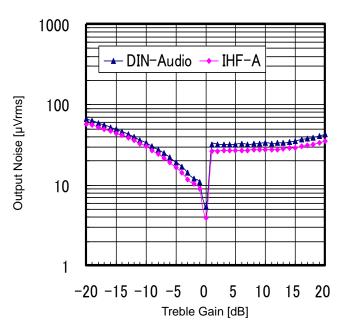


Figure 16. Output Noise vs Treble Gain

Typical Performance Curves - continued

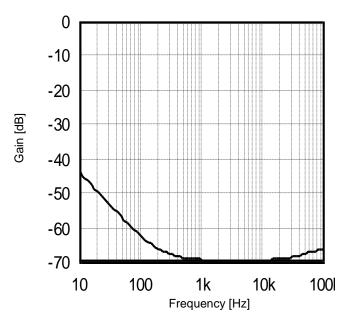


Figure 17. CMRR vs Frequency

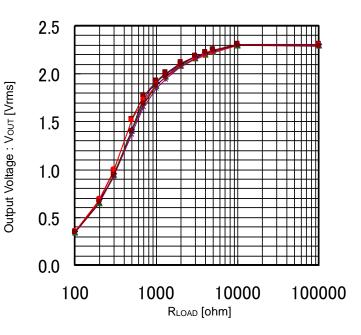


Figure 18. Output Voltage vs R_{LOAD}

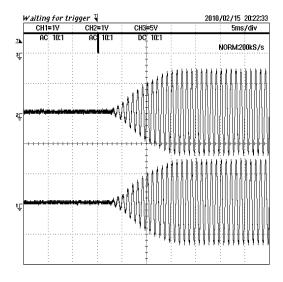


Figure 19. Advanced Switch 1

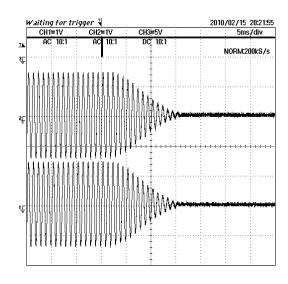


Figure 20. Advanced Switch 2

Timing Chart CONTROL SIGNAL SPECIFICATION

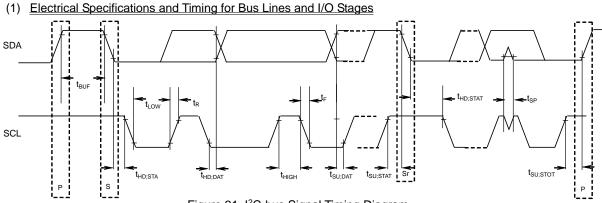


Figure 21. I²C-bus Signal Timing Diagram

Table 1 Characteristics of the SDA and SCL bus lines for I2C-bus devices (Ta=25°C, V_{CC}=8.5V)

	Parameter	Symbol	Fast-mode	Unit		
	Falametei	Syllibol	Min	Max	Offic	
1	SCL clock frequency	fscL	0	400	kHz	
2	Bus free time between a STOP and START condition	t BUF	1.3	-	μS	
3	Hold time (repeated) START condition. After this period, the first clock	4	0.6		μS	
3	pulse is generated	t _{HD;STA}	0.6	-	μΟ	
4	LOW period of the SCL clock	tLOW	1.3	-	μS	
5	HIGH period of the SCL clock	thigh	0.6	-	μS	
6	Set-up time for a repeated START condition	t _{SU;STA}	0.6	-	μS	
7	Data hold time:	thd;dat	0.06 (Note)	-	μS	
8	Data set-up time	tsu;dat	120	-	ns	
9	Set-up time for STOP condition	t _{SU;STO}	0.6	-	μS	

All values refer to VIH Min and VIL Max Levels (see Table 2).

(Note) A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH Min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

For $7(t_{\text{HD;DAT}})$, $8(t_{\text{SU;DAT}})$, make the setup in which the margin is full.

Table 2 Characteristics of the SDA and SCL I/O stages for I²C-bus devices

	Parameter	Symbol	Fast-mode	Unit	
	Falameter	Symbol	Min	Max	Offic
10	LOW level input voltage:	V_{IL}	-0.3	+1	V
11	HIGH level input voltage:	VIH	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	t _{SP}	0	50	ns
13	LOW level output voltage: at 3mA sink current	V _{OL1}	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	l _l	-10	+10	μΑ

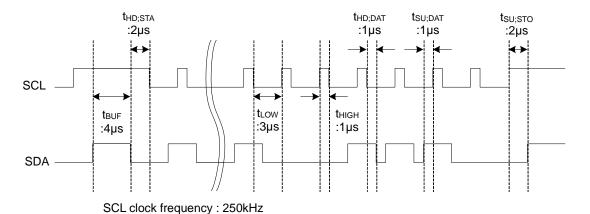


Figure 22. A Command Timing Example in the I²C Data Transmission

(2) <u>I²C BUS FORMAT</u>

	MSB LSB		MSB L	.SB	MSB	LSB							
S	Slave Address	Α	Select Address	Α	Data	1	Α	Р					
1bit	8bit	1bit	8bit	1bit	8bit	11	bit	1bit					
	S	= Sta	art condition (Recog	nition of	start bit)								
	Slave Address	= Recognition of slave address. The first 7 bits correspond to the slave address											
		Th	The least significant bit is "L" which corresponds to write mode.										
	Α	= AC	KNOWLEDGE bit (Recognit	tion of acknowled	lgement)							
	Select Address	= Se	lect address corresp	onding	to volume, bass o	or treble.							
	Data	= Da	ita on every volume	and tone) .								
	P	= Sto	on condition (Recog	nition of	stop hit)								

(3) I²C BUS Interface Protocol

(a) Basic Format

1-7									
S	Slave Address	Α	Seled	ct Address	Α	Da	ta	Α	Р
	MSB LS	В	MSB	LSB	N	1SB	LSE	3	

(b) Automatic Increment (Select Address increases (+1) according to the number of data.)

	S	Slave Add	ress	Α	Select Address		Α	Data	1	Α	Data2	Α		DataN	Α	Р
		MSB	LSB		MSB L	SB	I	MSB	LSE	3	MSB	LS	В	MSB	LS	В
((Exar	nple)														

- Data1 shall be set as data of address specified by Select Address.
 Data2 shall be set as data of address specified by Select Address +1.
- 3 DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration Unavailable for Transmission (In this case, only Select Address1 is set.)

7-/		mg and an entrance of the same transfer of the same											/_				
S	Sla	ave Address	Α	Select Add	ress1	Α	Dat	a A	Sele	ect A	Addres	ss 2	Α	Da	ıta	Α	Р
	MSB	LS	В	MSB	LSB		MSB	LSB	MSB			LSB	l M	1SB	LS	В	
		(Note) If any	data	a is transmitte	ed as Se	lec	t Add	ress 2	next to	da	ta, it is	reco	gni	zed			
	as data, not as Select Address 2.																

(4) Slave Address

MSB							LSB	
A6	A5	A4	A3	A2	A1	A0	R/W	
1	0	0	0	0	0	0	0	80H

(5) Select Address & Data

Itomo	Select Address	MSB Data LSB									
Items	(hex)	D7	D6	D5	D4	D3	D2	D1	D0		
Initial setup 1	01	Advanced switch ON/OFF	0	Input Gai	witch time of n/Volume /Super Bass ting	0	1		switch time //ute		
Initial setup 2	02	LPF Phase	0	0 Subwoofer Output Select 0 Subwoofer LPF fc					F f _C		
Initial setup 3	03	Front HPF Pass	Rear HPF Pass	Fro	nt / Rear HP	F f _C	0	1	0		
Input Selector	05	Full-diff Type	0	0 Input selector							
Input gain	06	Mute ON/OFF	0	0 Input Gain							
Volume gain	20		Volume Gain / Attenuation								
Fader 1ch Front	28		Fader Gain / Attenuation								
Fader 2ch Front	29	Fader Gain / Attenuation									
Fader 1ch Rear	2A				Fader Gain	/ Attenuatior	1				
Fader 2ch Rear	2B				Fader Gain	/ Attenuatior	1				
Fader Subwoofer	2C				Fader Gain	/ Attenuatior	1				
Mixing	30				Mixing Gain	/ Attenuation	n				
Bass setup	41	0	0	Bas	s f _O	0	0	Bas	ss Q		
Middle setup	44	0	0	Midd	lle fo	0	0	Midd	dle Q		
Treble setup	47	0	0	Treb	le fo	0	0	0	Treble Q		
Bass gain	51	Bass Boost/ Cut	0	0	Bass Gain						
Middle gain	54	Middle Boost/ Cut	0	0	Middle Gain						
Treble gain	57	Treble Boost/ Cut	0	0	Treble Gain						
Super Bass Gain	75	0	0	0	Super Bass Gain						
System Reset	FE	1	0	0	0	0	0	0	1		

Advanced switch

Note

- 1. The Advanced Switch works in the latch part while changing from one function to another.
- 2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.

$$01 \rightarrow 02 \rightarrow 03 \rightarrow 05 \rightarrow 06 \rightarrow 20 \rightarrow 28 \rightarrow 29 \rightarrow 2A \rightarrow 2B \rightarrow 2C$$

$$30 \rightarrow 41 \rightarrow 44 \rightarrow 47 \rightarrow 51 \rightarrow 54 \rightarrow 57 \rightarrow 75$$

- 3. Advanced switch is not used for the function of input selector and subwoofer output select, etc. Therefore, please apply mute on the side when changing these settings.
- 4. When using mute function of this IC at the time of changing input selector, please switch mute ON/OFF for waiting advanced-mute time.

Select address 01 (hex)

Time	MSB	Ac	Advanced switch time of Mute						
Tillie	D7	D6	D5	D4	D3	D2	D1	D0	
0.6msec	Advanaad		Advanced switch time of Input gain/Volume Tone/Fader/Super				0	0	
1.0msec	Advanced Switch	0			0	1	0	1	
1.4msec	ON/OFF						1	0	
3.2msec	ON/OFF		Bass/	Mixing			1	1	

		Λ -	l							
Time	Advanced switch time of Input MSB gain/Volume/Tone/Fader/ LSB Super Bass/Mixing									
	D7	D6	D5	D4	D3	D2	D1	D0		
4.7 msec	A al. (a.a. a.a. al	Advanced 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	0							
7.1 msec			0	1	0	1	Advanced switch			
11.2 msec			1	0			Time	of Mute		
14.4 msec	ON/OFF		1	1						

Mode	MSB	B Advanced switch ON/OFF LS								
IVIOGE	D7	D6	D5	D4	D3	D2	D1	D0		
OFF	0	0	of Input ga	switch time ain/Volume	0	1		ed switch		
ON	1	Ü		der/Super Mixing		,	Time	of Mute		

Select address 02(hex)

DOIGOT GGGGGGG								
fo	MSB Subwoofer LPF fc							LSB
TC TC	D7	D6	D5	D4	D3	D2	D1	D0
OFF						0	0	0
55Hz						0	0	1
85Hz	LPF	_	Subwoof	er Output	0	0	1	0
120Hz	Phase	0	Select		U	0	1	1
160Hz						1	0	0
Prohibition						Other setting		

Mode	MSB	MSB Subwoofer Output Select LSB									
Mode	D7	D6	D5	D4	D3	D2	D1	D0			
LPF			0	0							
Front	LPF Phase		0	1		Subwoofer LPF fc					
Rear		0	1	0	Ü						
Prohibition			1	1							

Phase	MSB	MSB LPF Phase							
Filase	D7	D6	D5	D4	D3	D2	D1	D0	
0°	0	0	Subwoofer output select		0 Subwoofer I		hwoofer I D	E fo	
180°	1	U					ubwoofer LPF fc		

Select address 03(hex)

COIOGE dadi 000 00(110X	/							
Mode	MSB			LSB				
iviode	D7	D6	D5	D4	D3	D2	D1	D0
55Hz			0	0	0			
85Hz	Front	Rear	0	0	1			
120Hz	HPF	HPF	1	1	0	0	1	0
160Hz	Pass	Pass	0	1	0			
Prohibition			(Other setting)			

Mode	MSB			Rear HPF					
iviode	D7	D6	D5	D4	D3	D2	D1	D0	
pass	Front	0	F		Г.	0	4	0	
NOT pass	HPF Pass	1	Fro	ont/Rear HP	F IC	0	1	0	

Mode	MSB	MSB Front HPF							
Mode	D7	D6	D5	D4	D3	D2	D1	D0	
pass	0	Rear		nt/Door UD	⊏ 4-	0	4	0	
NOT pass	1	HPF Pass	FIC	ont/Rear HP	r ic		l I	U	

Select address 05(hex)

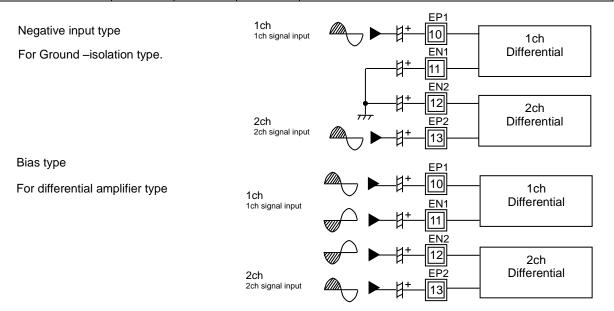
Ocicot addi	sect address collies)									
Mode			MSB		In	put S	electo	or		LSB
Mode	OUTF1	OUTF2	D7	D6	D5	D4	D3	D2	D1	D0
Α	A1	A2				0	0	0	0	0
В	B1	B2	Full- diff bias			0	0	0	0	1
С	C1	C2				0	0	0	1	0
D single	DP1	DP2				0	0	0	1	1
E single	EP1	EP2				0	0	1	0	0
A diff	A1	B1		0	0	0	1	1	1	1
C diff	B2	C2	type select			1	0	0	0	0
D diff	DP1	DP2	361661			0	0	1	1	0
E diff	EP1	EP2				0	0	1	1	1
Input SHORT					0	1	0	0	1	
Prohibition						Other setting				

Input SHORT : The input impedance of each input terminal is lowered from $100k\Omega(Typ)$ to $6~k\Omega(Typ)$.

(For quick charge of coupling capacitor)

Select address 05(hex)

Mode	MSB Full-diff Bias Type Select							
iviode	D7	D6	D5	D4	D3	D2	D1	D0
Negative Input	0	0	0		1	nput Selecto	r	
Bias	1] 0	0		- 1	riput Selecto	'1	



Select address 06 (hex)

Gain	MSB	<u> </u>		Inpu	ıt Gair	1		LSB	
Gairi	D7	D6	D5	D4	D3	D2	D1	D0	
0dB				0	0	0	0	0	
1dB				0	0	0	0	1	
2dB				0	0	0	1	0	
3dB				0	0	0	1	1	
4dB				0	0	1	0	0	
5dB				0	0	1	0	1	
6dB				0	0	1	1	0	
7dB				0	0	1	1	1	
8dB				0	1	0	0	0	
9dB				0	1	0	0	1	
10dB					0	1	0	1	0
11dB	Mute	0		0	1	0	1	1	
12dB	ON/OFF	0	0	0	1	1	0	0	
13dB				0	1	1	0	1	
14dB				0	1	1	1	0	
15dB				0	1	1	1	1	
16dB				1	0	0	0	0	
17dB				1	0	0	0	1	
18dB				1	0	0	1	0	
19dB				1	0	0	1	1	
20dB				1	0	1	0	0	
				1	1	0	1	1	
Prohibition				:	:	:	:	:	
				1	1	1	1	1	

Select address 06 (hex)

00.001 000	 -7							
Mode	MSB			LSB				
Wiode	D7	D6	D5	D4	D0			
OFF	0	0	0			Input Cain		
ON	1	0	U	Input Gain				

Select address 20, 28, 29, 2A, 2B, 2C (hex)

Gain & ATT	MSB	Vo	I, Fad	er Gai	n / Att	enuati	on	LSB
Gaill & Al I	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

Select address 30(hex)

Gain & ATT	MSB	ľ	dixing	Gain	/ Atter	nuation	า	LSB
Gaill & All	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	1	0	0	0
7dB	0	1	1	1	1	0	0	1
6dB	0	1	1	1	1	0	1	0
5dB	0	1	1	1	1	0	1	1
:		:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	:	:	:
	1	1	1	1	1	1	1	0
MIX OFF	1	1	1	1	1	1	1	1

(Note) See the precaution on P30 together, too.

: Initial co	ndition
--------------	---------

Select address 41(hex)

J	addicoo + I (IICX)								
	Q factor	MSB	MSB		Bass Q factor				LSB
	Qiacioi	D7	D6	D5	D4	D3	D2	D1	D0
	0.5							0	0
	1.0	0	0	Pag	ss fo	0	0	0	1
	1.5		0	Das	55 10		0	1	0
	2.0							1	1

f a	MSB			Bas	s fo			LSB
IO	D7	D6	D5	D4	D3	D2	D1	D0
60Hz			0	0				
80Hz]	_	0	1	_	0	Ва	ass actor
100Hz] 0	0	1	0	0	U	Q fa	actor
120Hz			1	1				

Select address 44(hex)

	/							
Q factor	MSB		Middle Q facto			ctor		LSB
Qiacioi	D7	D6	D5	D4	D3	D2	D1	D0
0.75							0	0
1.0	_		Middle fo		0		0	1
1.25	U	0	ivilde	ale io	0	U	1	0
1.5							1	1

•	MSB			Middl	LSB			
10	D7	D6	D5	D4	D3	D2	D1	D0
500Hz			0	0				
1kHz	_	0	0	1	_		Mid	ddle
1.5kHz] 0	U	1	0	0 0		Q factor	
2.5kHz			1	1				

Select address 47 (hex)

Q factor	MSB	1	Tı	Treble (Q factor		LSB
Q lactor	D7	D6	D5	D4	D3	D2	D1	D0
0.75	0	0	Trob	lo fo	0	0	0	0
1.25	U	U	rrec	ole fo	U	U	U	1

fo	MSB			Treble fo					
TO	D7	D6	D5	D4	D3	D2	D1	D0	
7.5kHz			0	0					
10kHz	0	0	0	1	0	0	0	Treble Q factor	
12.5kHz	U	U	1	0	U	U	0	Q factor	
15kHz			1	1					

Select address 51, 54, 57 (hex)

Gain	MSB		Bass/l	<u> </u>	LSB			
Gairi	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB	1			0	0	0	0	1
2dB	1			0	0	0	1	0
3dB	1			0	0	0	1	1
4dB	1			0	0	1	0	0
5dB	1			0	0	1	0	1
6dB	1			0	0	1	1	0
7dB	1			0	0	1	1	1
8dB	1			0	1	0	0	0
9dB	1		0	0	1	0	0	1
10dB	Bass/			0	1	0	1	0
11dB	Middle/			0	1	0	1	1
12dB	Treble	0		0	1	1	0	0
13dB	Boost	Ü		0	1	1	0	1
14dB	/cut			0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB	1			1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	:	:	:
1 TOTALOTT				1	1	1	1	0
				1	1	1	1	1

Mode	MSB	Ва	ss/Mid	ddle/T	reble l	3oost/	Cut	LSB
Mode	D7	D6	D5	D4	D2	D1	D0	
Boost	0	0	0		Bacc/I	Middle/Trobl	o Gain	
Cut	1	0 0 Bass/Middle/Treble Gain						

Select address 75 (hex)

Gain	MSB		Sı	ıper B	LSB			
Gain	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB]	_	_	0	1	0	1	1
12dB	0	0	0	0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:.	:	:	:
				1	1	1	1	1

(Note) About Super Bass, the above Gain is for in indication purposes. Actual Gain (=20log (Vout/Vin)) is different. Refer to P31 to P34 for the details.

· Initia	I condition
. II II ua	i conuntion

(6) About Power ON Reset

Built-in IC initialization is made during power ON of the supply voltage. Please send initial data to all addresses at supply voltage on. And please turn ON mute until this initial data is sent.

Daramatar	Cumbal	•	Limit		Linit	Conditions
Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Rise Time of VCC	trise	33	-	-	µsec	V _{CC} rise time from 0V to 5V
VCC Voltage of Release Power ON Reset	V _{POR}	-	4.1	-	V	

Application Information

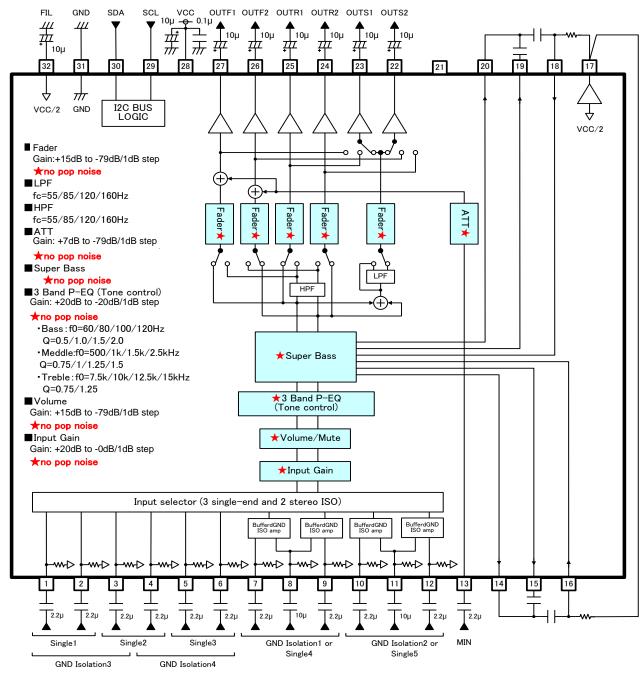
Function and Specifica	tions								
Function	Specifications								
	Stereo input Single-End/Differential								
	· Single-End/Differential								
	(Possible to set the number of single-end/ differential as follows)								
Input selector	Mode 1	Single-End 0	Differential 4						
	Mode 2	1	3						
	Mode 3 Mode 4	3	2						
	Mode 5	5	0						
		Table.1 Combination	of input selector	•					
Input gain	· +20dB to 0dB (1dB	step)							
p 4.1 94	· Possible to use "Ad	vanced switch" for preven	ention of switching nois	se.					
Mute	Possible to use "Ad	vanced switch" for preven	ention of switching nois	se.					
Volume	· +15dB to -79dB (1d								
	Possible to use "Ad	vanced switch" for preven	ention of switching nois	se.					
	· +20dB to -20dB (1d	B step)							
Bass	· Q=0.5, 1, 1.5, 2								
	 f₀=60, 80, 100, 120Hz Possible to use "Advanced switch" for prevention of switching noise. 								
		•	ention of switching nois	Se.					
	· +20dB to -20dB (1dB step)								
Middle	· Q=0.75, 1, 1.25, 1.5								
	· fo=500, 1k, 1.5k 2.5kHz								
		vanced switch" for preve	ention of switching nois	Se.					
	+20dB to -20dB (1d	B step)							
Treble	· Q=0.75, 1.25								
	· f _O =7.5k, 10k, 12.5k, 15kHz								
		vanced switch" for preve	ention of switching nois	Se.					
Fader	+15dB to -79dB(1dl	• **	and a second second						
		vanced switch" for preve	ention of switching hols	Se.					
LPF	• fc=55/85/120/160Hz	•							
HPF	• Phase shift (0°/180°) • fc=55/85/120/160Hz, pass								
1111	Monaural input	., pass							
Mixing	+7dBdB to -79dB (1	dB sten) -∞dB							
XIIIg	-	vanced switch" for preve	ention of switching nois	se.					
	+20dB to 0dB (1dB								
Super Bass	,	vanced switch" for preve	ention of switching nois	se.					
	. 555.5.5 to 455 714	and a strict for prove	2311 31 37710111119 11010						

2. Volume / Fader Volume / Mixing ATT Attenuation Data

(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15	0	1	1	1	0	0	0	1	-33	1	0	1	0	0	0	0	1
+14	0	1	1	1	0	0	1	0	-34	1	0	1	0	0	0	1	0
+13	0	1	1	1	0	0	1	1	-35	1	0	1	0	0	0	1	1
+12	0	1	1	1	0	1	0	0	-36	1	0	1	0	0	1	0	0
+11	0	1	1	1	0	1	0	1	-37	1	0	1	0	0	1	0	1
+10	0	1	1	1	0	1	1	0	-38	1	0	1	0	0	1	1	0
+9	0	1	1	1	0	1	1	1	-39	1	0	1	0	0	1	1	1
+8	0	1	1	1	1	0	0	0	-40	1	0	1	0	1	0	0	0
+7	0	1	1	1	1	0	0	1	-41	1	0	1	0	1	0	0	1
+6	0	1	1	1	1	0	1	0	-42	1	0	1	0	1	0	1	0
+5	0	1	1	1	1	0	1	1	-43	1	0	1	0	1	0	1	1
+4	0	1	1	1	1	1	0	0	-44	1	0	1	0	1	1	0	0
+3	0	1	1	1	1	1	0	1	-45	1	0	1	0	1	1	0	1
+2	0	1	1	1	1	1	1	0	-46	1	0	1	0	1	1	1	0
+1	0	1	1	1	1	1	1	1	-47	1	0	1	0	1	1	1	1
0	1	0	0	0	0	0	0	0	-48	1	0	1	1	0	0	0	0
-1	1	0	0	0	0	0	0	1	-49	1	0	1	1	0	0	0	1
-2	1	0	0	0	0	0	1	0	-50	1	0	1	1	0	0	1	0
-3	1	0	0	0	0	0	1	1	-51	1	0	1	1	0	0	1	1
-4	1	0	0	0	0	1	0	0	-52	1	0	1	1	0	1	0	0
-5	1	0	0	0	0	1	0	1	-53	1	0	1	1	0	1	0	1
-6	1	0	0	0	0	1	1	0	-54	1	0	1	1	0	1	1	0
-7	1	0	0	0	0	1	1	1	-55	1	0	1	1	0	1	1	1
-8	1	0	0	0	1	0	0	0	-56	1	0	1	1	1	0	0	0
-9 -10	1	0	0	0	1	0	<u>0</u>	0	-57 -58	1	0	1	1	1	0	1	0
-10	1	0	0	0	1	0	1	1	-56 -59	1	0	1	1	1	0	1	1
-12	1	0	0	0	1	1	0	0	-60	1	0	1	1	1	1	0	0
-13	1	0	0	0	1	1	0	1	-61	1	0	1	1	1	1	0	1
-14	1	0	0	0	1	1	1	0	-62	1	0	1	1	1	1	1	0
-15	1	0	0	0	1	1	1	1	-63	1	0	1	1	1	1	1	1
-16	1	0	0	1	0	0	0	0	-64	1	1	0	0	0	0	0	0
-17	1	0	0	1	0	0	0	1	-65	1	1	0	0	0	0	0	1
-18	1	0	0	1	0	0	1	0	-66	1	1	0	0	0	0	1	0
-19	1	0	0	1	0	0	1	1	-67	1	1	0	0	0	0	1	1
-20	1	0	0	1	0	1	0	0	-68	1	1	0	0	0	1	0	0
-21	1	0	0	1	0	1	0	1	-69	1	1	0	0	0	1	0	1
-22	1	0	0	1	0	1	1	0	-70	1	1	0	0	0	1	1	0
-23	1	0	0	1	0	1	1	1	-71	1	1	0	0	0	1	1	1
-24	1	0	0	1	1	0	0	0	-72	1	1	0	0	1	0	0	0
-25	1	0	0	1	1	0	0	1	-73	1	1	0	0	1	0	0	1
-26	1	0	0	1	1	0	1	0	-74	1	1	0	0	1	0	1	0
-27	1	0	0	1	1	0	1	1	-75	1	1	0	0	1	0	1	1
-28	1	0	0	1	1	1	0	0	-76	1	1	0	0	1	1	0	0
-29	1	0	0	1	1	1	0	1	-77	1	1	0	0	1	1	0	1
-30	1	0	0	1	1	1	1	0	-78	1	1	0	0	1	1	1	0
-31	1	0	0	1	1	1	1	1	-79	1	1	0	0	1	1	1	1
-32	1	0	1	0	0	0	0	0	-∞	1	1	1	1	1	1	1	1

Adjustable range of mixing ATT is +7dB to -∞dB.

3. Application Circuit



*About single input 1 to 3 it is possible to change from single input to GND Isolation input 3,4.

*About GND Isolation1 and GND Isolation2, it is possible to change from differential input to single input 4 to 5.

Figure 23. BD37544FS

Unit $R: [\Omega]$ C:[F]

Notes on wiring

- ①Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.
- ②GND lines should be one-point connected.
 ③Wiring pattern of Digital should be away from that of Analog unit and cross-talk should not be acceptable.
- 4SCL and SDA lines of I²C BUS should not be parallel if possible.
 - The lines should be shielded, if they are adjacent to each other.
- Sanalog input lines should not be parallel if possible. The lines should be shielded, if they are adjacent.
- ⑥Please short Pins 15-16, and Pins 18-19 if the Super Bass is not used.

Power Dissipation

About the thermal design of the IC

Characteristics of an IC have a great deal to do with the temperature at which it is used, and exceeding absolute maximum ratings may degrade and destroy elements. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

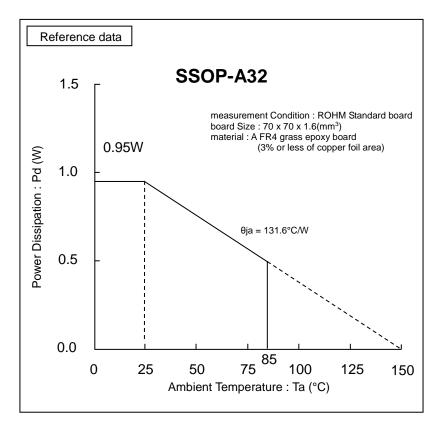


Figure 24. Temperature Derating Curve (Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

I/O Equivalent Circuits

O Equivale	ent Circuits			
Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
1 2 3 4 5	A1 A2 B1 B2 C1 C2	4.25	VCC Δ 100KΩ	A terminal for signal input. The input impedance is 100kΩ(Typ).
7 8 9 10 11 12	DP1 DN DP2 EP1 EN	4.25	VCC	Input terminal available to ingle/Differential mode. The input impedance is 250kΩ(Typ).
16 18	SBB1 SBB2	-	VCC VO VO	An input terminal for Super Bass
15 17 19 22 23 24 25 26 27	SBA1 SBBIAS SBA2 OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25	VCC GND GND	A terminal for Super Bass and fader, Subwoofer output.
14 20	SBC1 SBC2	4.25	VCC Θ 3KΩ Θ Θ Θ	An output terminal for Super Bass.

 $Values \ in \ the \ pin \ explanation \ and \ input/output \ equivalent \ circuit \ are \ reference \ values \ only \ and \ are \ not \ guaranteed.$

I/O Equivalent Circuits - continued

Terminal	nt Circuits Terminal	Terminal		
No.	Name	Voltage	Equivalent Circuit	Terminal Description
28	VCC	8.5		Power supply terminal.
29	SCL	-	VCC O 1.65V	A terminal for clock input of I ² C BUS communication.
30	SDA		VCC O O J J J 1.65	A terminal for data input of I ² C BUS communication.
31	GND	0		Ground terminal.
32	FIL	4.25	VCC Solve So	1/2 VCC terminal. Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.
13	MIN	4.25	VCC Δ A B 27KΩ	A terminal for signal input. The input impedance is 27kΩ(typ).

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes - continued

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

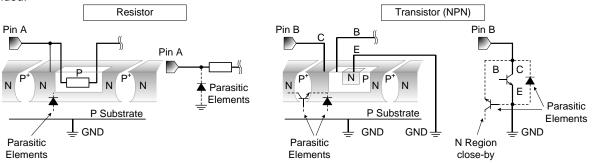
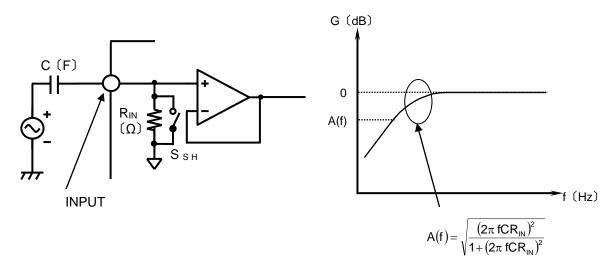


Figure 25. Example of monolithic IC structure

13. About Signal Input

(a) About Input Coupling Capacitor Constant Value

The constant value of input coupling capacitor C(F) is decided with respect to the input impedance $R_{IN}(\Omega)$ at the input signal terminal of the IC. The first HPF characteristic of RC is composed.



(b) About the Input Selector SHORT

SHORT mode is the command which makes switch S_{SH} =ON of input selector part so that the input impedance R_{IN} of all terminals becomes small. Switch S_{SH} is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of S_{SH} and makes it low impedance, please use it at no signal condition.

Operational Notes - continued

14. About MIX

(1) About Specification of Fader -∞ at MIX ON.

Mix_signal is added to Main_signal after Fader_Gain(+15dB to -79dB) like the figure. When Fader is set at -∞, the signal after a MIX signal is added is done with MUTE because the -∞ circuit of Fader is in the step after the addition circuit

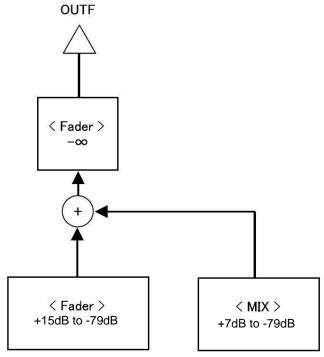
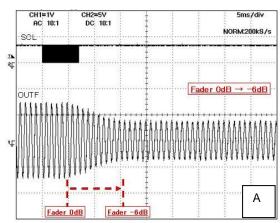


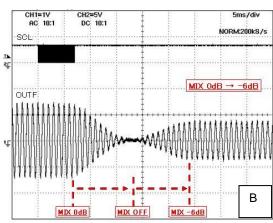
Figure 26. About Front Fader and MIX

(2) About Advanced Switching of MIX Gain/ATT

When advanced switching of MIX_Gain/ATT works, MIX goes a switching movement that it passes through the state of MIX_OFF like in B figure below (from current setting of MIX_Gain/ATT to MIX_OFF to a target setting of MIX_Gain/ATT).



Fader_Gain/ATT 0dB to -6dB advanced switching



MIX_Gain/ATT 0dB to -6dB advanced switching

Figure 27. Advanced Switching Movement when MIX_Gain/ATT is Changed

Operational Notes - continued

15. About Super Bass Circuit

The (the following Super Bass) which strengthens a low band like the graph below a can be realized by composing an external circuit with the pin 14 to 20 as shown in Figure 28.

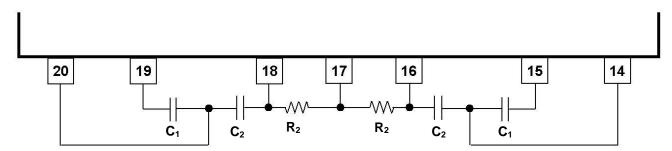


Figure 28. Super Bass circuit

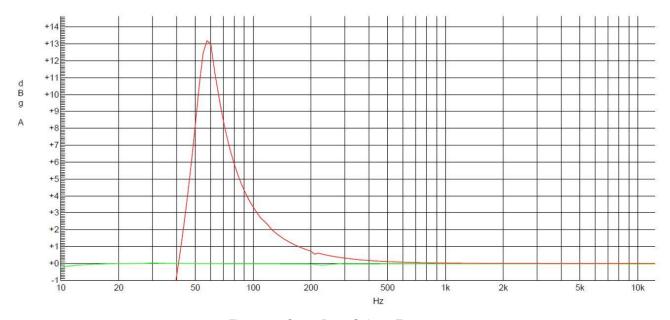


Figure 29. Super Bass Gain vs Frequency

(a) <u>Gain Step Width becomes a Logarithm</u> When a setup of Gain is made 0,1,2,3,5,7,11,20dB, it becomes the following (bottom right) character. $(C_1=0.047\mu\text{F},\,C_2=0.1\mu\text{F},\,R_1=3k\Omega,\,R_2=560k\Omega)$

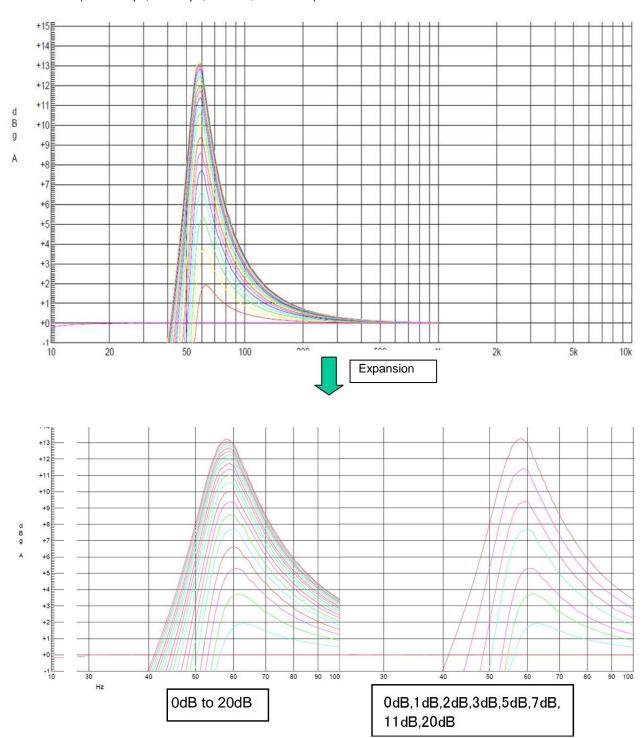
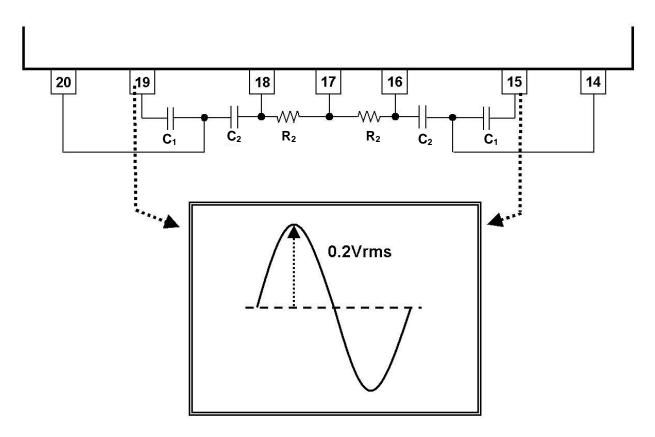


Figure 30. About Gain step of Super Bass

(b) You must take level diagram into consideration so that output may not do a clip

 $\frac{\text{Example }(C_1 = 0.047 \mu \text{F, } C_2 = 0.1 \mu \text{F, } R_2 = 560 \text{kohm, } V_{\text{CC}} = 8.5 \text{V})}{\text{To prevent output clipping due to amplification when Super Bass is used, adjust the level diagram with }}$ volume until the Tone output level becomes less than 0.2Vrms.



Please adjust so that the maximum level of the Tone output becomes less than 0.2Vrms. (at Vcc=8.5V)

Figure 31. Super Bass Level Diagram

(c) About fo and Gain of Super Bass

 f_0 and Gain of Super Bass deviates due to the deviation of the value of C_1 , C_2 , R_2 (Components with the outside),

R₁ (the resistance built in IC).

Example: Super Bass Gain – frequency characteristic at Dispersion condition of C_1 , C_2 , $R_2 \pm 5\%$, $R_1 \pm 30\%$ ($C_1 = 0.047 \mu F$, $C_2 = 0.1 \mu F$, $R_1 = 3 kohm$, $R_2 = 560 kohm$, Super Bass Gain=20dB)

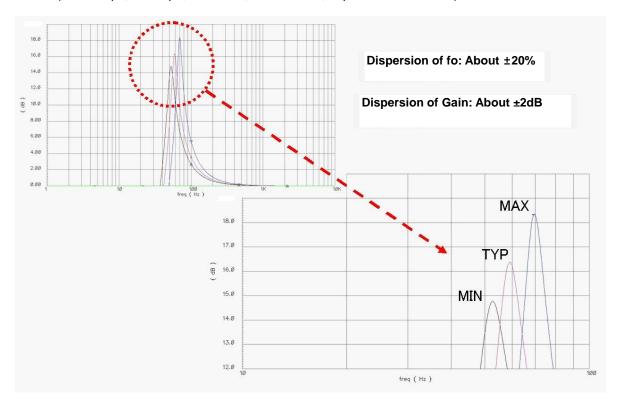
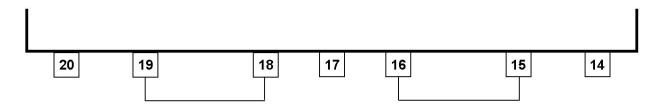


Figure 32. Dispersion of fo and Gain of Super Bass

(d) How to Deal with Pins of Super Bass when not used

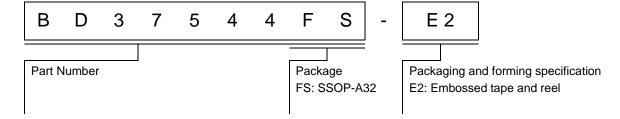
Short Pins 15 to 16, Pins 18 to 19 as shown in Figure 33 when the Super Bass function is not used.



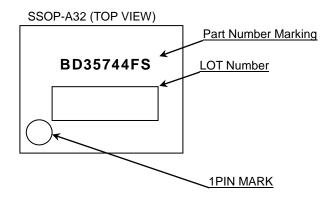
Short Pin 15 to 16, Pin 18 to 19

Figure 33. How to Deal with Pins of Super Bass when not used

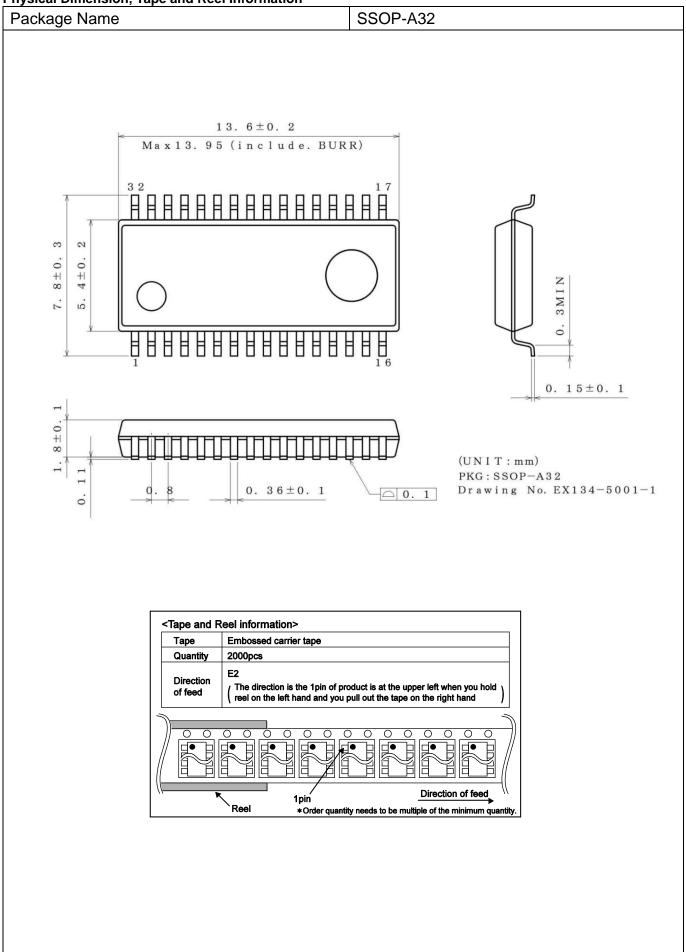
Ordering Information



Marking Diagram



Physical Dimension, Tape and Reel Information



Revision History

Date	Revision	Changes
16.Dec.2015	001	New Release

Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCIII	CLASSIIb	П 20
CLASSIV	CLASSⅢ	CLASSⅢ	- CLASSIII

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

Precaution Regarding Intellectual Property Rights

- 1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data.
- 2. ROHM shall not have any obligations where the claims, actions or demands arising from the combination of the Products with other articles such as components, circuits, systems or external equipment (including software).
- 3. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the Products or the information contained in this document. Provided, however, that ROHM will not assert its intellectual property rights or other rights against you or your customers to the extent necessary to manufacture or sell products containing the Products, subject to the terms and conditions herein.

Other Precaution

- 1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.
- 2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
- In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
- The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

Notice-PGA-E Rev.002

General Precaution

- 1. Before you use our Products, you are requested to care fully read this document and fully understand its contents. ROHM shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of a ny ROHM's Products against warning, caution or note contained in this document.
- 2. All information contained in this docume nt is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sale s representative.
- 3. The information contained in this doc ument is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate an d/or error-free. ROHM shall not be in an y way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.

Notice – WE © 2015 ROHM Co., Ltd. All rights reserved. Rev.001

ПОСТАВКА ЭЛЕКТРОННЫХ КОМПОНЕНТОВ

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001 Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru moschip.ru_6 moschip.ru_4 moschip.ru_9